

Ming-Tzer Lin

List of Publications by Year in descending order

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Version: 2024-02-01

48
papers

489
citations

840776

11
h-index

713466

21
g-index

48
all docs

48
docs citations

48
times ranked

450
citing authors

#	ARTICLE	IF	CITATIONS
1	Heat dissipation design and analysis of high power LED array using the finite element method. <i>Microelectronics Reliability</i> , 2012, 52, 905-911.	1.7	131
2	Design of fins with a grooved heat pipe for dissipation of heat from high-powered automotive LED headlights. <i>Energy Conversion and Management</i> , 2019, 180, 550-558.	9.2	52
3	Temperature-dependent microtensile testing of thin film materials for application to microelectromechanical system. <i>Microsystem Technologies</i> , 2006, 12, 1045-1051.	2.0	25
4	Novel Microtensile Method for Monotonic and Cyclic Testing of Freestanding Copper Thin Films. <i>Experimental Mechanics</i> , 2010, 50, 55-64.	2.0	21
5	Driving forces for texture transformation in thin Ag films. <i>Acta Materialia</i> , 2016, 105, 495-504.	7.9	20
6	Enhanced growth of the Ni ₃ Sn ₄ phase at the Sn/Ni interface subjected to strains. <i>Scripta Materialia</i> , 2011, 65, 691-694.	5.2	19
7	Viscoelastic mechanical properties measurement of thin Al and Al-Mg films using bulge testing. <i>Thin Solid Films</i> , 2016, 618, 2-7.	1.8	18
8	Optical micro-paddle beam deflection measurement for electrostatic mechanical testing of nano-scale thin film application to MEMS. <i>Microsystem Technologies</i> , 2010, 16, 1131-1137.	2.0	17
9	Cyclic creep and fatigue testing of nanocrystalline copper thin films. <i>Surface and Coatings Technology</i> , 2013, 215, 393-399.	4.8	15
10	Effects of Electrical Current and External Stress on the Electromigration of Intermetallic Compounds Between the Flip-Chip Solder and Copper Substrate. <i>Journal of Electronic Materials</i> , 2018, 47, 35-48.	2.2	14
11	Design and development of a novel paddle test structure for the mechanical behavior measurement of thin films application for MEMS. <i>Microsystem Technologies</i> , 2009, 15, 1207-1216.	2.0	13
12	The influence of vanadium alloying on the elevated-temperature mechanical properties of thin gold films. <i>Thin Solid Films</i> , 2007, 515, 7919-7925.	1.8	10
13	Monotonic and fatigue testing of freestanding submicron thin beams application for MEMS. <i>Microsystem Technologies</i> , 2008, 14, 1041-1048.	2.0	10
14	Novel full range vacuum pressure sensing technique using free decay of trapezoid micro-cantilever beam deflected by electrostatic force. <i>Microsystem Technologies</i> , 2012, 18, 1903-1908.	2.0	10
15	The thermal evaluation of the substrate mixed with microencapsulated phase change materials for MEMS packaging applications. <i>Microsystem Technologies</i> , 2011, 17, 693-699.	2.0	8
16	Effect of temperature on energy loss and internal friction in nanocrystalline copper thin films. <i>Surface and Coatings Technology</i> , 2014, 260, 272-278.	4.8	8
17	Design and development of sub-micron scale specimens with electroplated structures for the microtensile testing of thin films. <i>Microsystem Technologies</i> , 2007, 13, 1559-1565.	2.0	7
18	Effect of Loading Stress on the Growth of Cu/Sn Intermetallic Compounds at High Temperatures. <i>Journal of Electronic Materials</i> , 2015, 44, 604-611.	2.2	7

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19	Digital image correlation of SEM images for surface deformation of CMOS IC. <i>Microelectronic Engineering</i> , 2018, 201, 16-21.	2.4	7
20	A study of the phase transformation of low temperature deposited tantalum thin films using high power impulse magnetron sputtering and pulsed DC magnetron sputtering. <i>Surface and Coatings Technology</i> , 2022, 436, 128288.	4.8	7
21	Three-Phase Linear Motor Heat Transfer Analysis Using the Finite-Element Method. <i>Heat Transfer Engineering</i> , 2010, 31, 617-624.	1.9	6
22	Measurement of static and dynamic mechanical behavior of micro and nano-scale thin metal films: using micro-cantilever beam deflection. <i>Microsystem Technologies</i> , 2011, 17, 721-730.	2.0	6
23	The study of internal friction in nanocrystalline Ag and Au thin films. <i>Thin Solid Films</i> , 2014, 570, 262-267.	1.8	6
24	Using Digital Image Correlation on SEM Images of Strain Field after Ion Beam Milling for the Residual Stress Measurement of Thin Films. <i>Materials</i> , 2020, 13, 1291.	2.9	6
25	Novel heat dissipation design for light emitting diode applications. <i>Microsystem Technologies</i> , 2010, 16, 519-526.	2.0	5
26	Use of Digital Image Correlation Method to Measure Bio-Tissue Deformation. <i>Coatings</i> , 2021, 11, 924.	2.6	5
27	Design an Electroplated Frame Freestanding Specimen for Microtensile Testing of Submicron thin TaN and Cu Film. <i>Materials Research Society Symposia Proceedings</i> , 2006, 914, 1.	0.1	4
28	Simulation of a high-power LED lamp for the evaluation and design of heat dissipation mechanisms. <i>Microsystem Technologies</i> , 2016, 22, 523-529.	2.0	4
29	The Effects of Stresses and Interfaces on Texture Transformation in Silver Thin Films. <i>Nanomaterials</i> , 2022, 12, 329.	4.1	4
30	Mechanical Properties and Residual Stress Measurement of TiN/Ti Duplex Coating Using HiPIMS TiN on Cold Spray Ti. <i>Coatings</i> , 2022, 12, 759.	2.6	4
31	Using Taguchi method to obtain the optimal design of heat dissipation mechanism for electronic component packaging. <i>Microelectronics Reliability</i> , 2016, 65, 131-141.	1.7	3
32	Study on Electromigration Effects and IMC Formation on Cu-Sn Films Due to Current Stress and Temperature. <i>Applied Sciences (Switzerland)</i> , 2020, 10, 8893.	2.5	3
33	Influence of External Strain on the Growth of Interfacial Intermetallic Compounds Between Sn and Cu Substrates. <i>Journal of Electronic Materials</i> , 2012, 41, 3309-3319.	2.2	2
34	Time and temperature dependent mechanical behavior of Al/Ti thin films application for MEMS. , 2017, , .		2
35	Size Effects in Internal Friction of Nanocrystalline Aluminum Films. <i>Materials</i> , 2021, 14, 3401.	2.9	2
36	Measurement of Effects of Different Substrates on the Mechanical Properties of Submicron Titanium Nickel Shape Memory Alloy Thin Film Using the Bulge Test. <i>Micromachines</i> , 2021, 12, 85.	2.9	2

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37	Mechanical property measurement of nano-scale metal films on the novel paddle cantilever beams using four step phase-shifting method. , 2008, , .		1
38	Linear energy control of laser drilling and its application in the repair of TFT-LCD bright pixels. Microsystem Technologies, 2012, 18, 1909-1915.	2.0	1
39	Constructing high-power LED lamp model to evaluate different heat dissipation mechanism design. , 2014, , .		1
40	Evaluating heat dissipation in edge-lit LED backlight module using Taguchi method. , 2014, , .		1
41	Planar copper-tin inter-metallic film formation on strained substrates. Microelectronics Reliability, 2014, 54, 1378-1383.	1.7	1
42	<i>Ab-Initio</i> Study of (111) to (001) Texture Transformation in Ag Thin Films. Materials Transactions, 2019, 60, 437-440.	1.2	1
43	Process nano scale mechanical properties measurement of thin metal films using a novel paddle cantilever test structure. , 2008, , .		0
44	Recent Development of Using Optical Methods to Measure the Mechanical Properties of Thin Films. , 2014, , .		0
45	OS5-2-5 Micro scale monotonic and tension fatigue testing of spring-bridge freestanding thin films application for MEMS. The Abstracts of ATEM International Conference on Advanced Technology in Experimental Mechanics Asian Conference on Experimental Mechanics, 2007, 2007.6, OS5-2-5-1- OS5-2-5-6.	0.0	0
46	OS06-2-2 Thickness dependence of the internal frictions in aluminum thin film. The Abstracts of ATEM International Conference on Advanced Technology in Experimental Mechanics Asian Conference on Experimental Mechanics, 2011, 2011.10, _OS06-2-2-.	0.0	0
47	In Situ Energy Loss and Internal Friction Measurement of Nanocrystalline Copper Thin Films Under Different Temperature. Conference Proceedings of the Society for Experimental Mechanics, 2015, , 67-73.	0.5	0
48	Digital Image Correlation on FIB Ring-Core Measurement on Residual Stress of Thin Films. The Abstracts of ATEM International Conference on Advanced Technology in Experimental Mechanics Asian Conference on Experimental Mechanics, 2019, 2019, 1008B1145.	0.0	0